

Product / Package Information

Package	SOT23
Body Size	
Lead Count	6
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration
Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.06 E-03	87.00	870000	40.22	402245
Thermosets	Phenol Resin	Proprietary	3.65 E-04	4.50	45000	2.08	20806
Thermosets	Epoxy Resin 1	Proprietary	2.44 E-04	3.00	30000	1.39	13871
Thermosets	Epoxy Resin 2	Proprietary	2.44 E-04	3.00	30000	1.39	13871
Others	Crystalline silica	14808-60-7	1.62 E-04	2.00	20000	0.92	9247
Other inorganic materials	Carbon Black	1333-86-4	4.06 E-05	0.50	5000	0.23	2312
Subtotal			8.12 E-03	100.0	1000000	46.24	462351

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	7.53 E-03	97.5	975000	42.87	428897
Copper & its alloys	Iron	7439-89-6	1.81 E-04	2.35	23500	1.03	10333
Copper & its alloys	Zinc	7440-66-6	9.27 E-06	0.12	1200	0.05	528
Copper & its alloys	Phosphorus	7723-14-0	2.32 E-06	0.03	300	0.01	132
Subtotal			7.72 E-03	100	1000000	43.97	439689

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.80 E-05	100	1000000	0.44	4441

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.02 E-04	100	1000000	2.29	22915

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.70 E-04	99.99	1000000	0.97	9679

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	1.00 E-03	100	1000000	5.69	56940

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.64 E-05	80.50	805000	0.32	3209
Other organic materials	Carbocyclic Acrylates	Proprietary	7.00 E-06	10.00	100000	0.04	399
Other organic materials	Bismaleimide resin	Proprietary	2.10 E-06	3.00	30000	0.01	120
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	2.10 E-06	3.00	30000	0.01	120
Others	Additive	Proprietary	2.10 E-06	3.00	30000	0.01	120
Other organic materials	Dicumyl peroxide	80-43-3	3.50 E-07	0.50	5000	0.002	20
Subtotal			7.00 E-05	100.00	1000000	0.40	3988

Package Totals	Weight (g)	Percentage (%)	PPM
	1.76 E-02	100	1000000

Control ID: MS010611EPKG497

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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